



# Performance of Rad-Hard Quad Receivers at Extreme Temperatures



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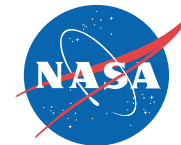
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## Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- **Characterize the electrical performance and reliabilities as potential space electronic parts under extreme low and high temperature (-125 ~ +150°C) environments extending nominal device specifications (-55 ~ +125°C).**
- **Identify needed enabling technologies to improve operation, reliability, and lifetime of future space missions such as Mars.**



# Presentation outline



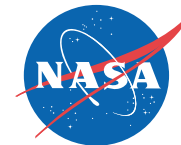
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## Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- **Purpose**
- **Rad-Hard Quad Receivers**
- **Test Method**
- **Results**
- **Conclusions**
- **Recommendations**



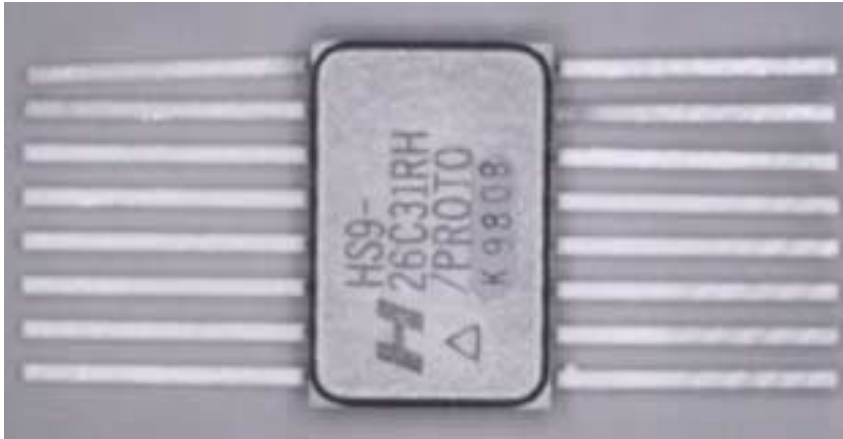
# Rad-Hard Quad Receiver



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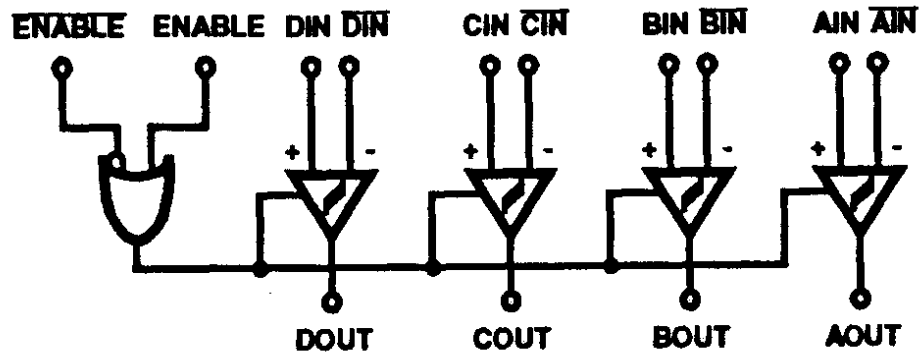
- A quad differential line receiver designed for digital data transmission (**logic input buffer**) over balanced lines and meets the requirements of RS-422
- Radiation Hardened CMOS processing for low power consumption, high speed, and reliable operation in the most severe radiation environments.
  - Total Dose: 100KRAD (Si)
  - Single Event Upset (SEU)
  - Single Event Latch-up (SEL)
  - Thresholds:  $>100$  MeV/mg/cm<sup>2</sup>
- Supply current at low and high state
- Dynamic supply current
- Input current at high and low state
- Output high and low voltages
- Tri-state low and high current
- Propagation delays and transition times.

## Rad-Hard Quad Receivers



- **Radiation hardened RS-422 line receiver**
- **Has CMOS enable pin input levels and accepts TTL-level enable signals**
- **The two circuits are identical except for the configuration of the logic input buffers**
- **The HS-26C32RH has the same input characteristics (impedance, hysteresis, failsafe) as commercial types.**

# Functional Diagram



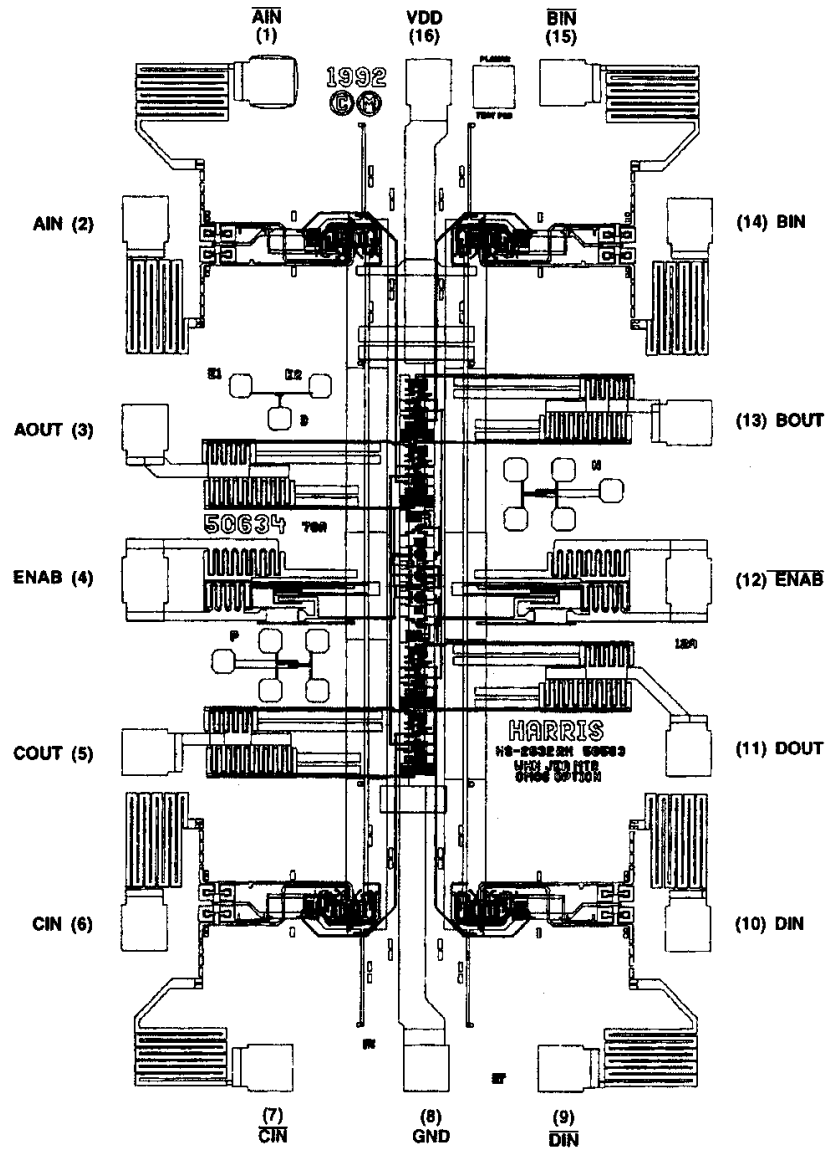
TRUTH TABLE

DEVICE POWER ON/OFF	INPUTS			OUTPUT
	ENABLE	ENABLE	INPUT	OUT
ON	0	1	X	HI-Z
ON	1	X	$VID \geq VTH$ (Max)	1
ON	1	X	$VID \leq VTH$ (Min)	0
ON	X	0	$VID \geq VTH$ (Max)	1
ON	X	0	$VID \leq VTH$ (Min)	0
ON	1	X	Open	1
ON	X	0	Open	1

## Die Characteristics

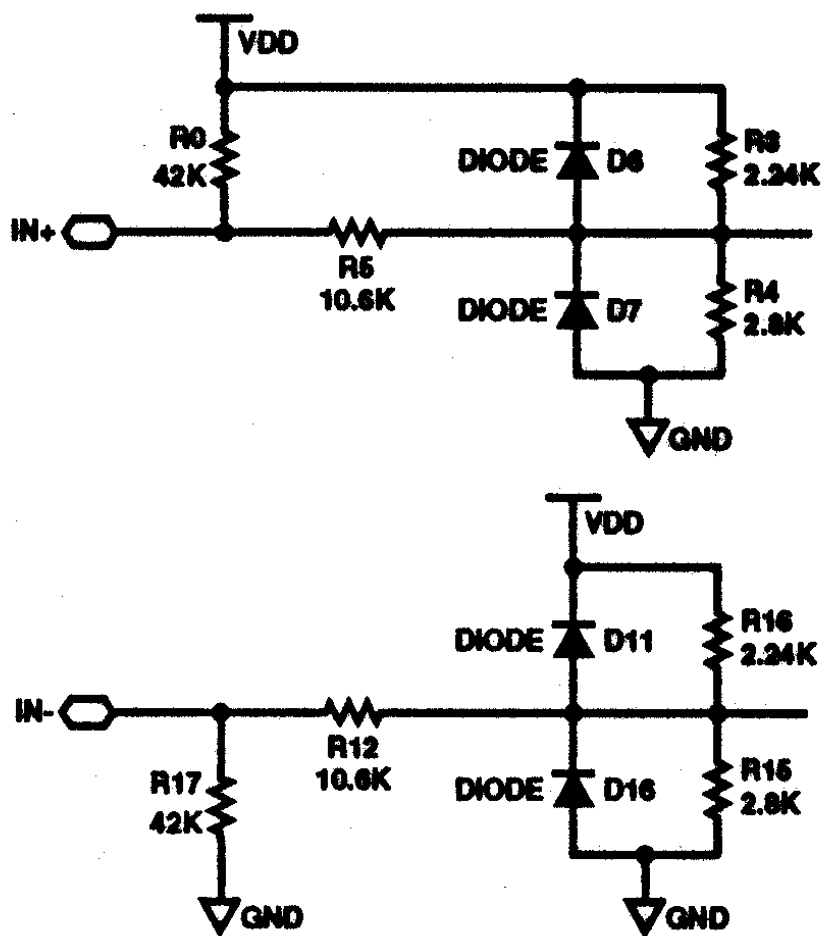
- **Die Dimensions: 2140 $\mu\text{m}$  x 3290  $\mu\text{m}$  x 533 $\mu\text{m}$   $\pm$  25.4 $\mu\text{m}$**
- **Backside Finish: Silicon**
- **Passivation:**
  - **Type: SiO<sub>2</sub>**
    - » **Thickness: 800nm  $\pm$  100nm**
- **Metallization:**
  - **M1: Mo/TiW**
    - » **Thickness: 580nm**
  - **M2: Al/Si/Cu**
    - » **Thickness: 1000nm  $\pm$  100nm**
- **Substrate Potential: Internally connected to V<sub>DD</sub>**
- **Worst Case Current Density: < 2.0E5 A/cm<sup>2</sup>**
- **Transistor Count: 315**
- **Process: Radiation Hardened CMOS, AVLSI**

# Die Layout





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# Parasitic Diodes for Each Output

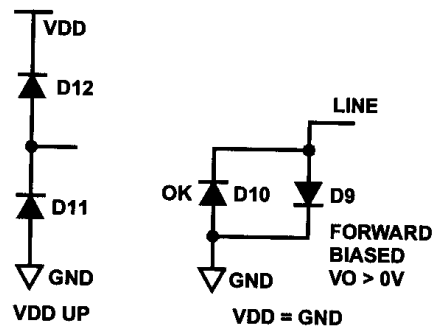
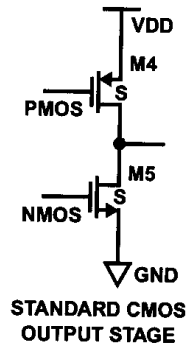
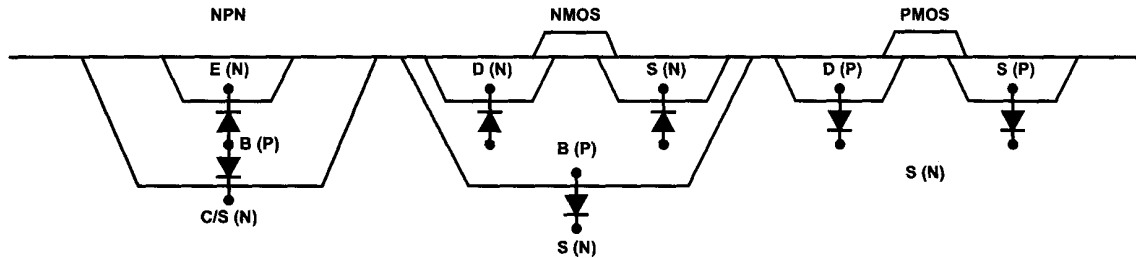


FIGURE 3A.

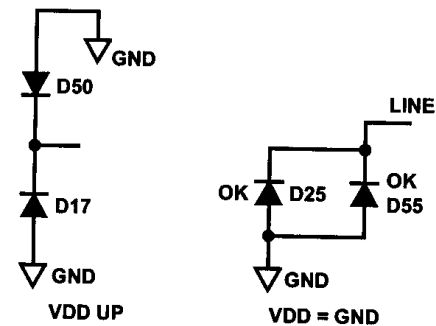
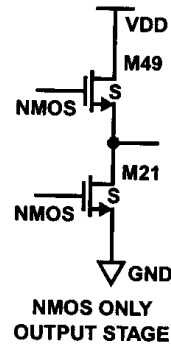


FIGURE 3B.

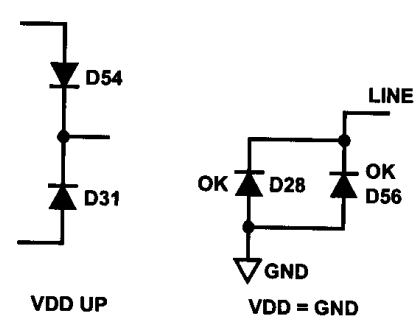
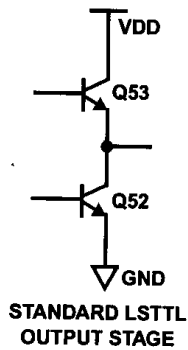


FIGURE 3C.

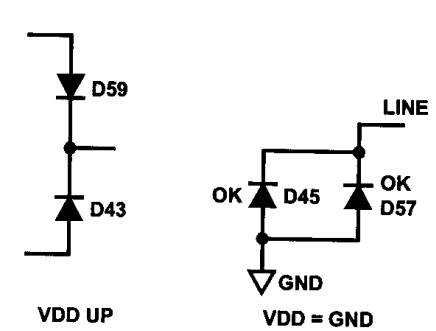
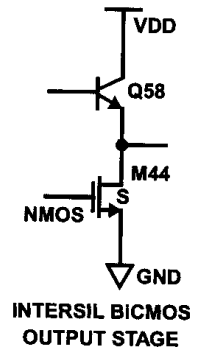
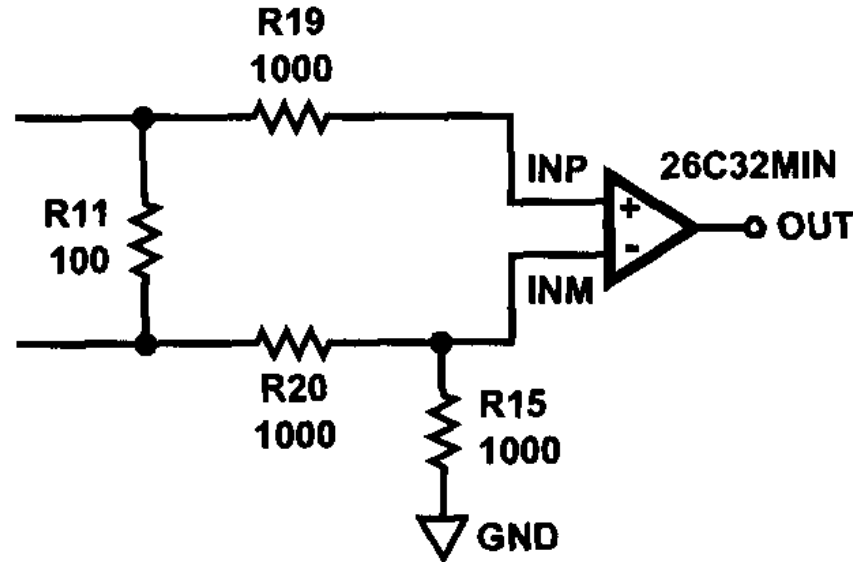


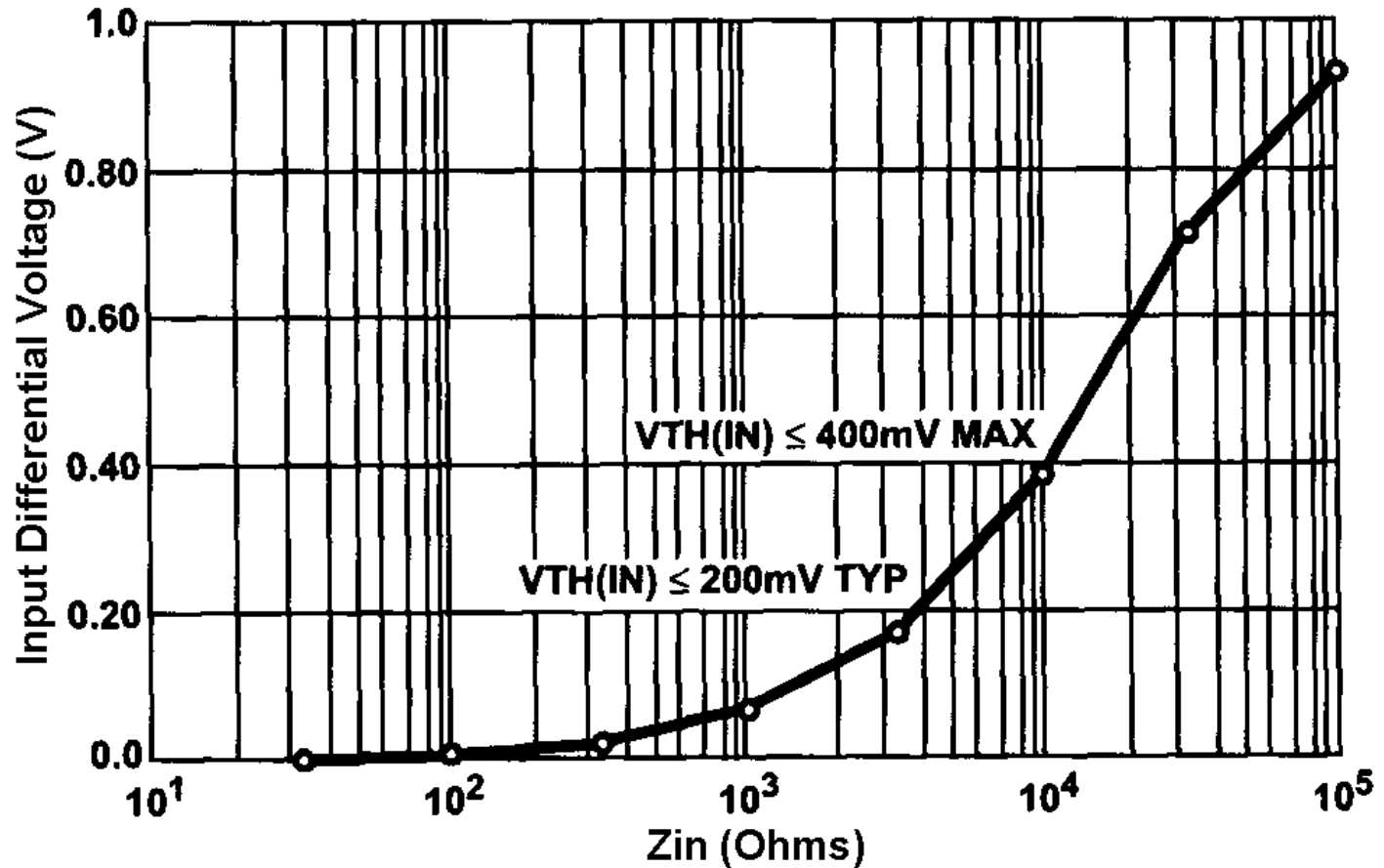
FIGURE 3D.

# Adequate input differential voltage for open line fault conditions

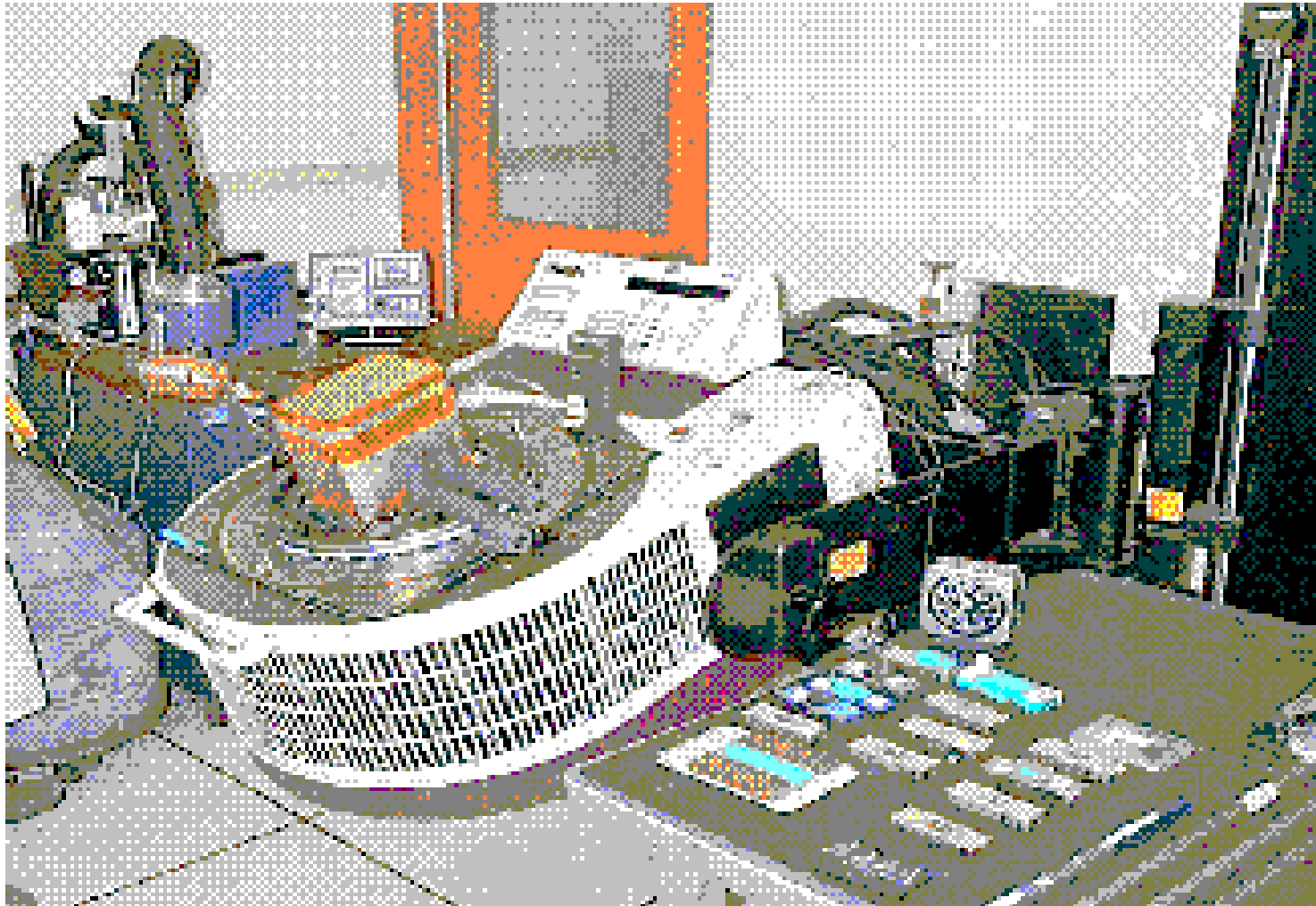


- Produces too small an input differential voltage in the open-line fault condition
- The internal input bias network is shunted by the termination resistor
- The internal input bias network is supplemented externally to compensate for the termination resistor

# Input Fail/Safe Differential vs $Z_{in}$ (Open)

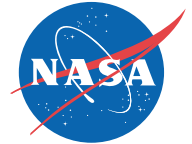


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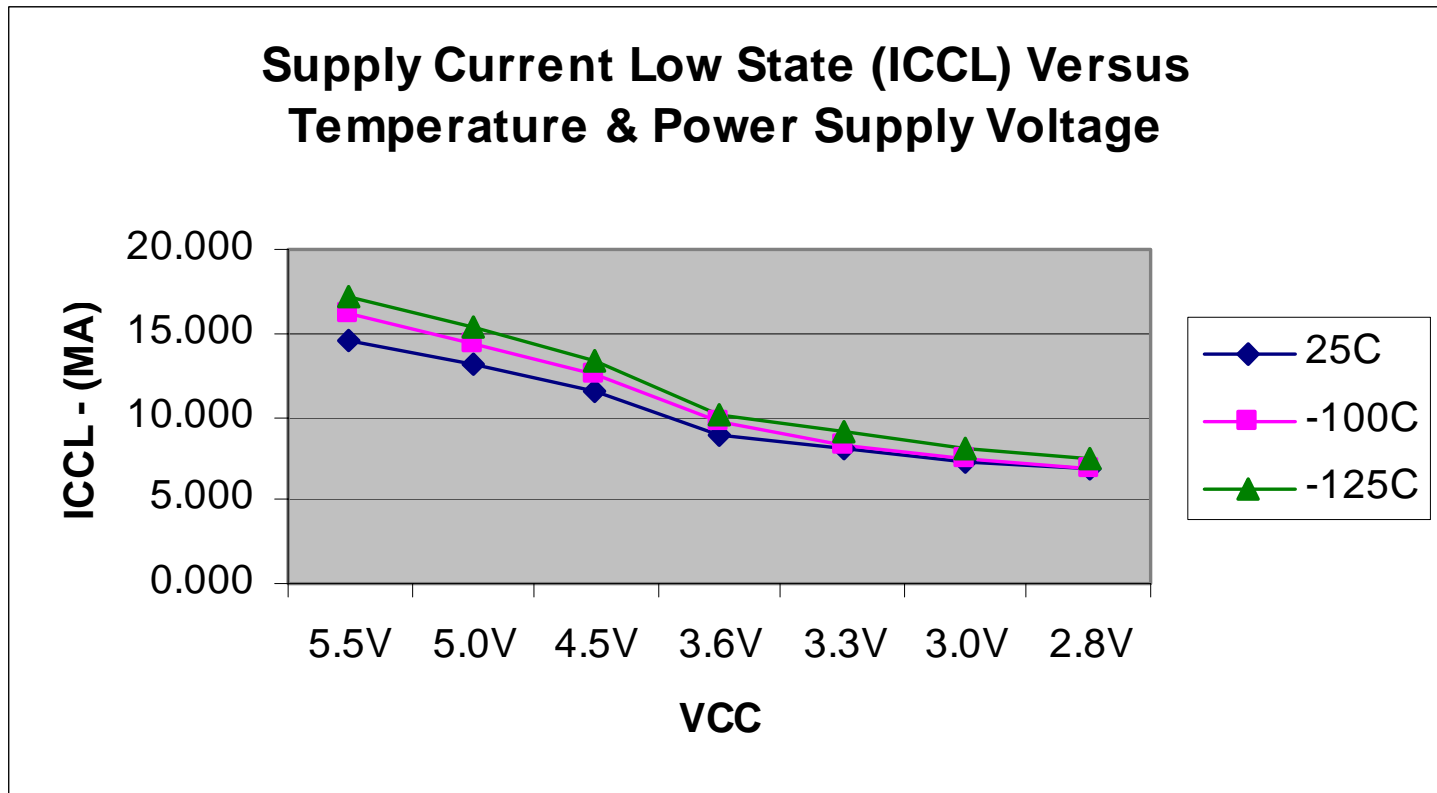




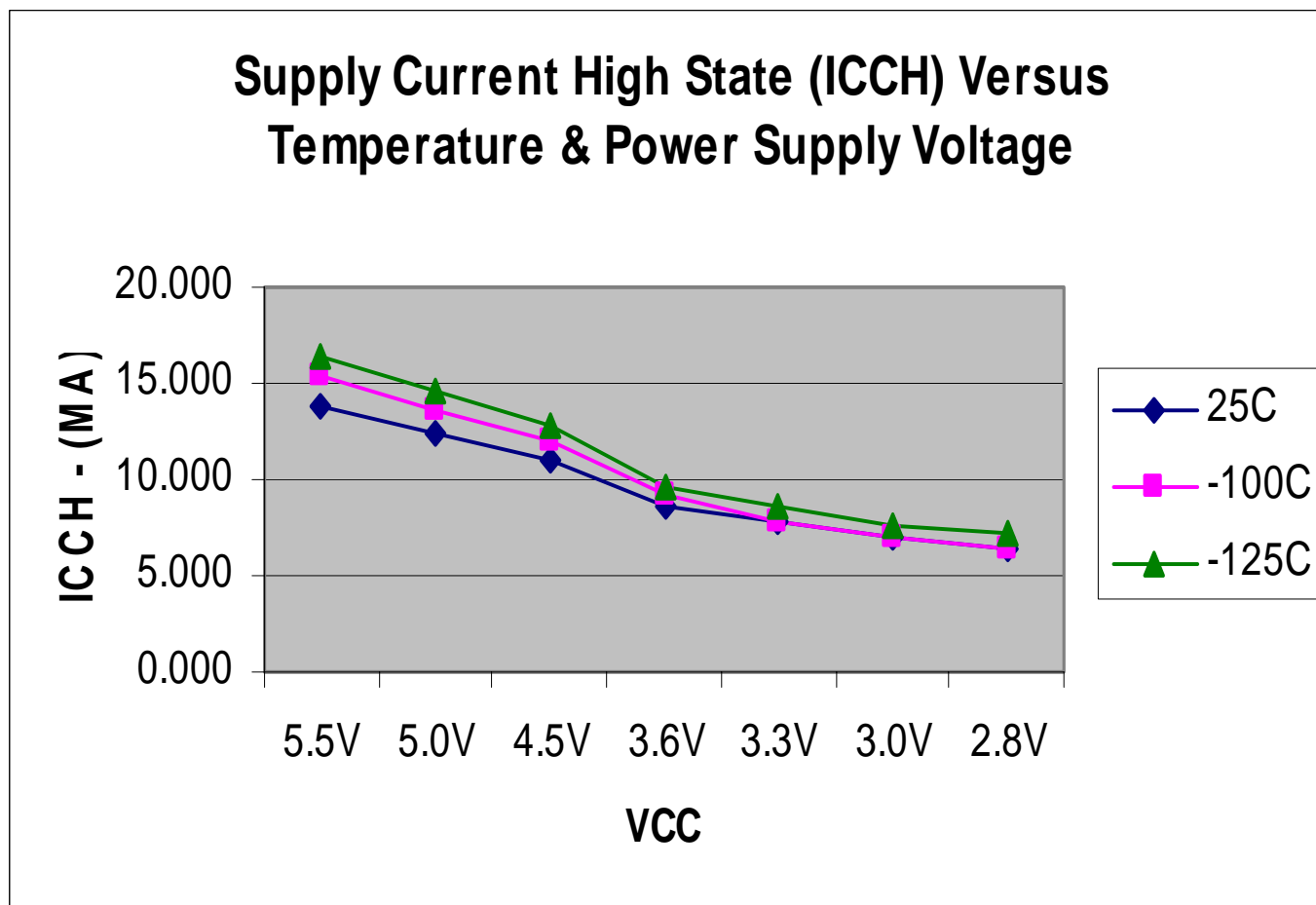
# Characteristics of the quiescent power supply currents



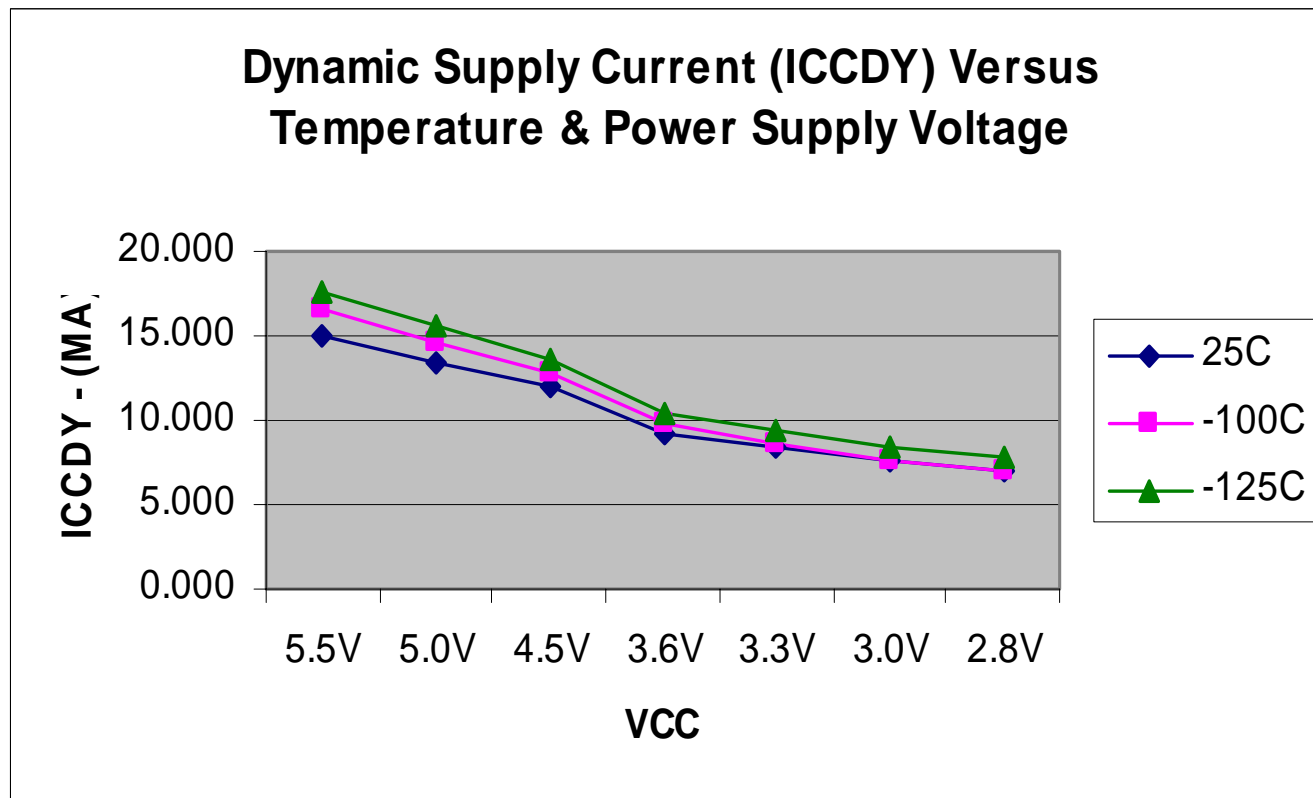
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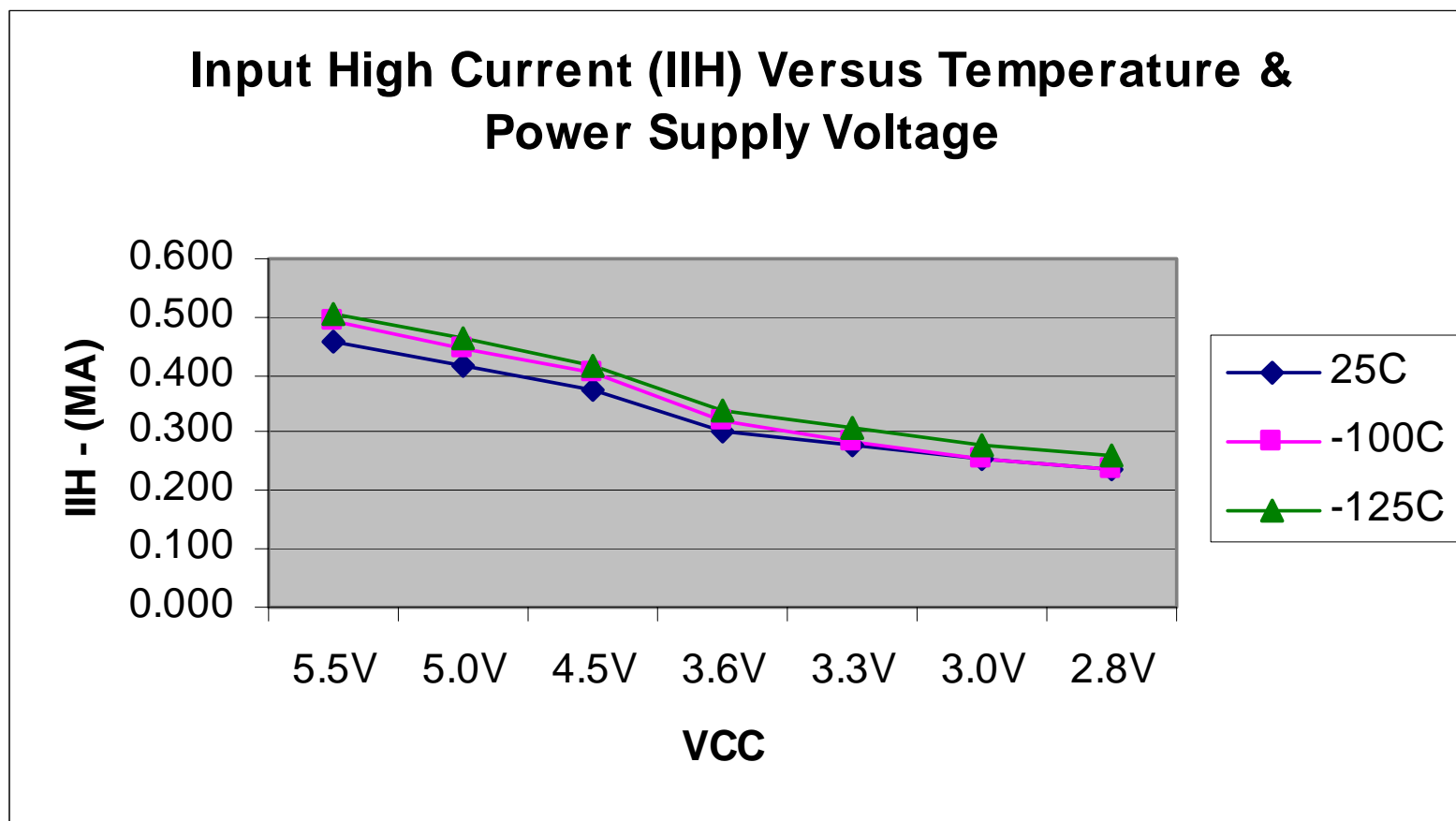


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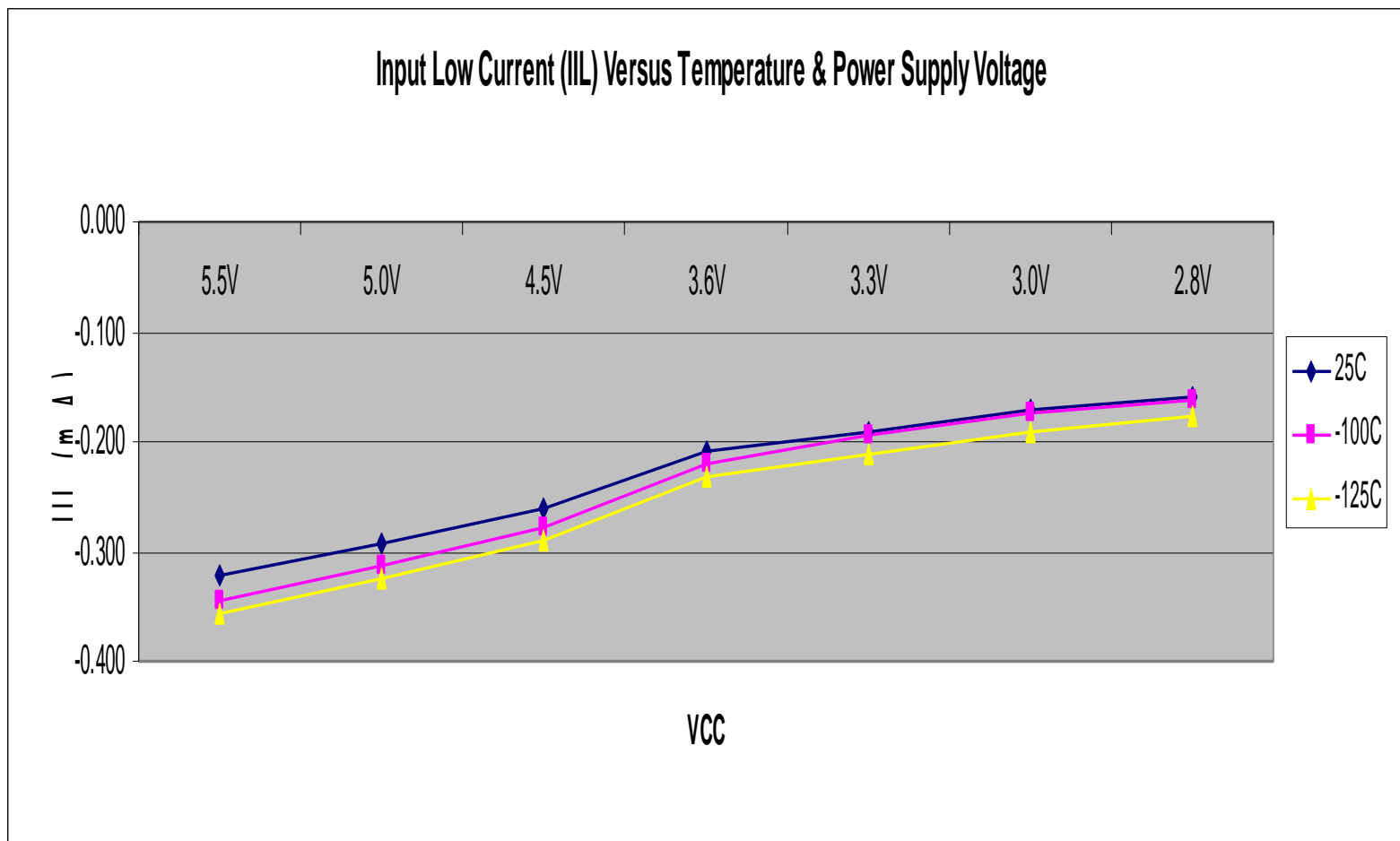




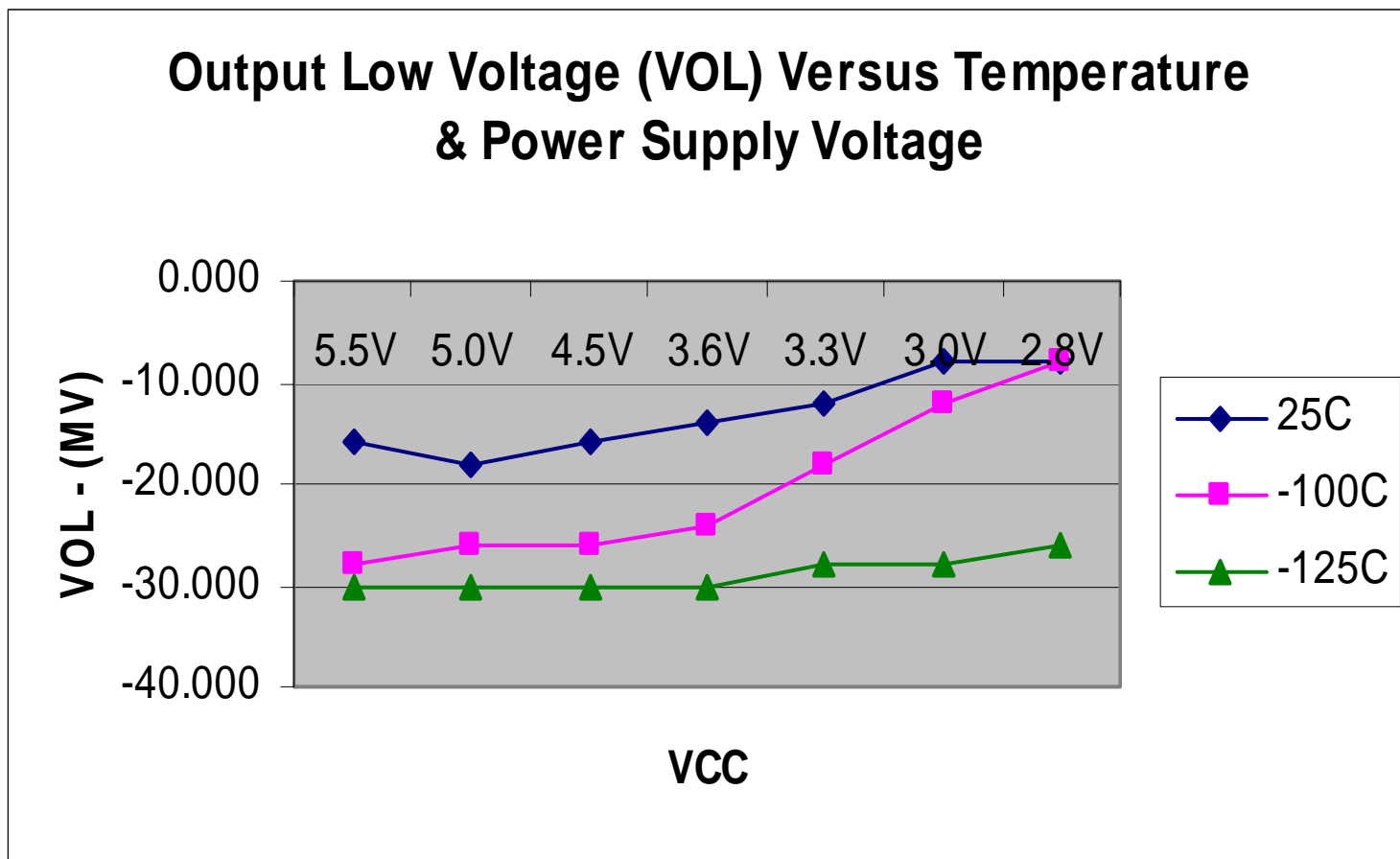
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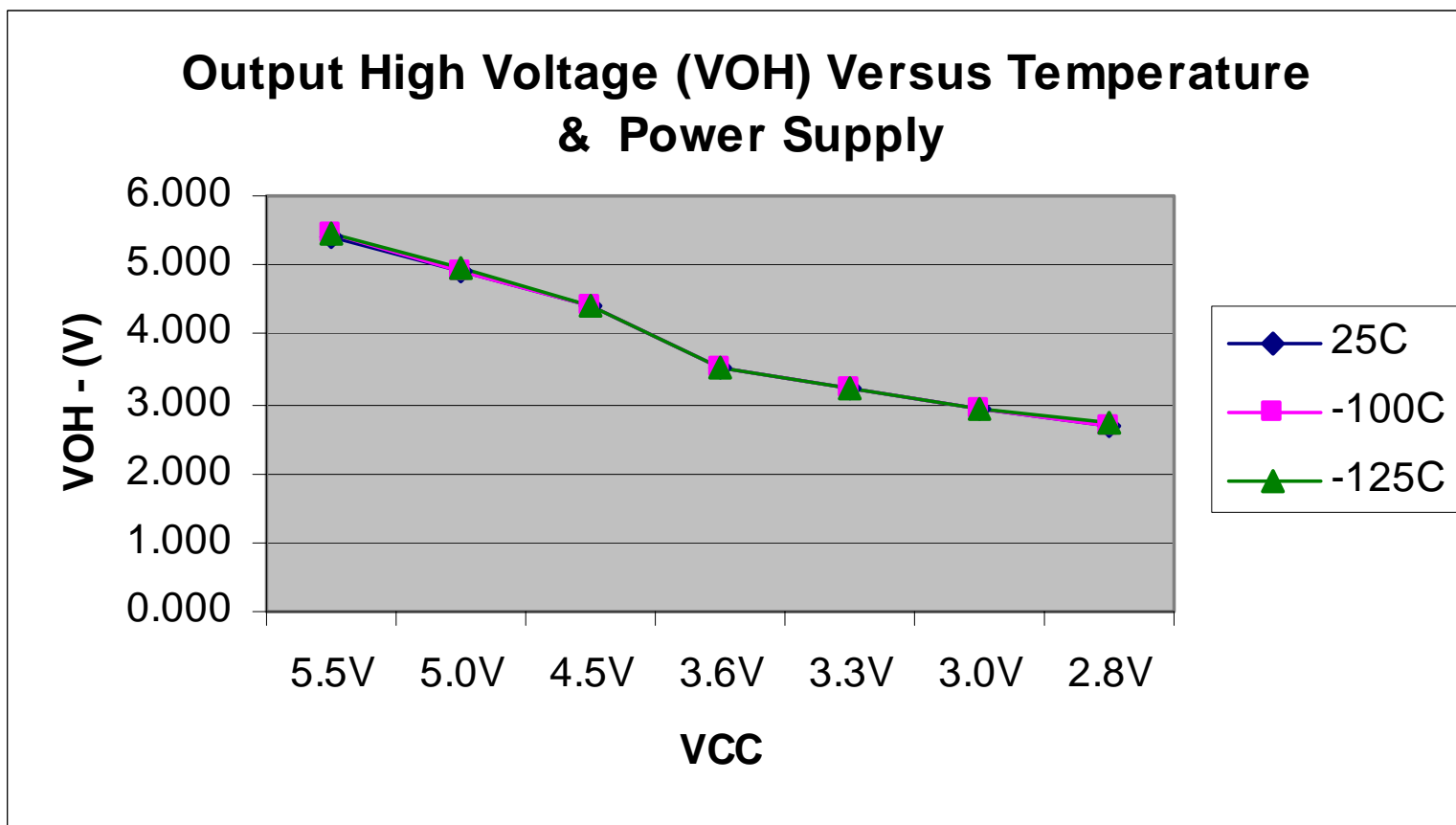
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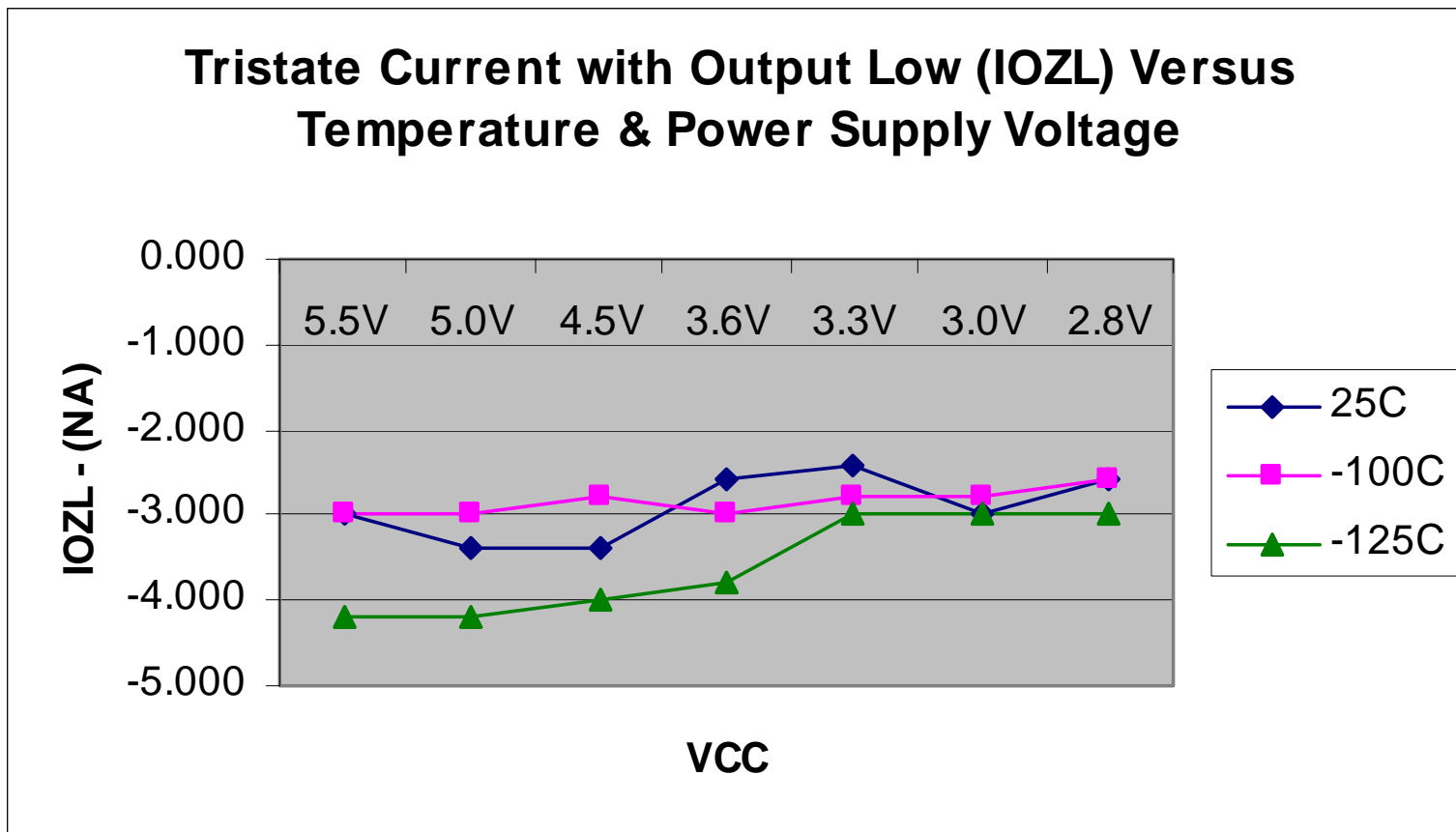
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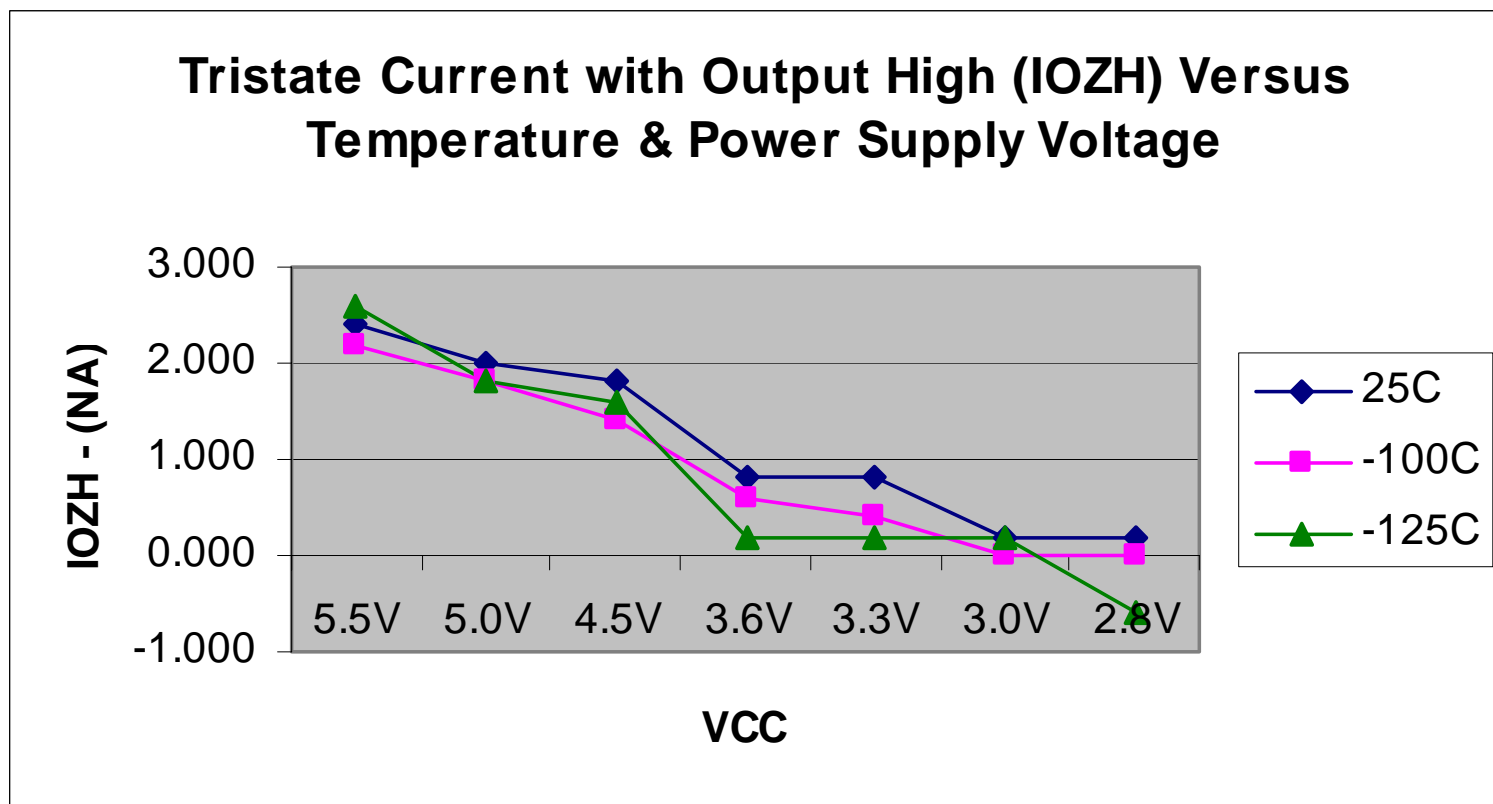
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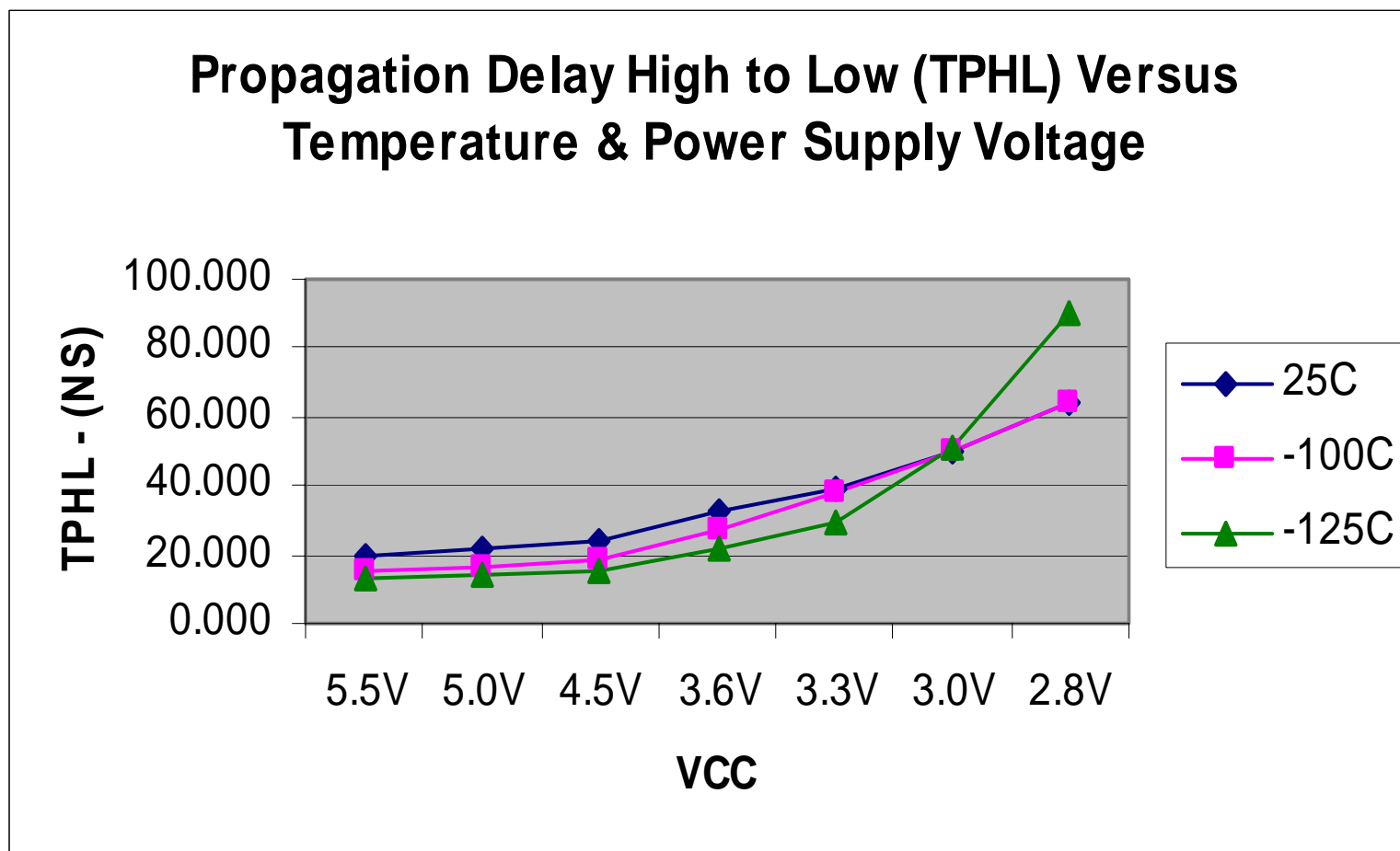
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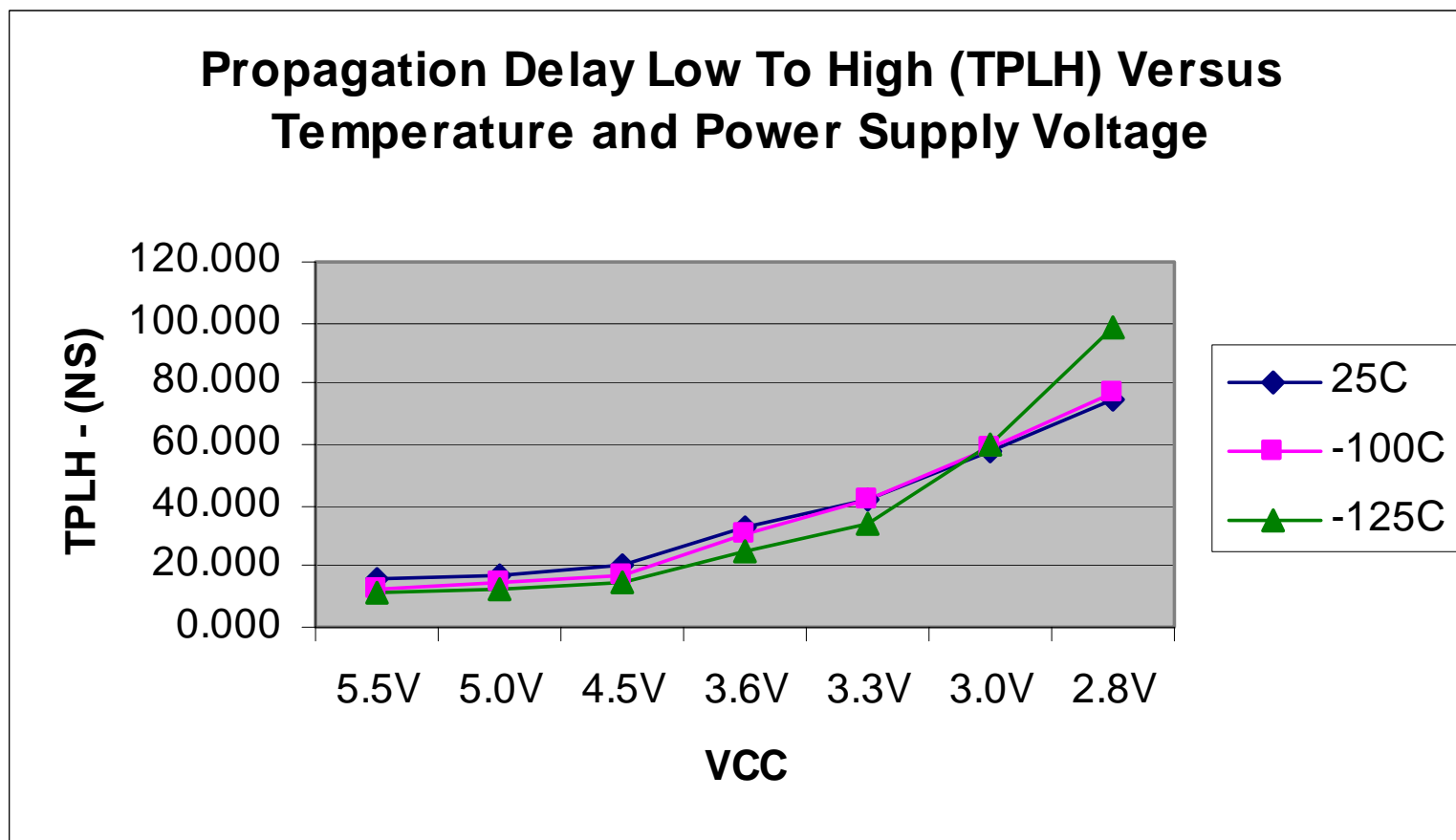
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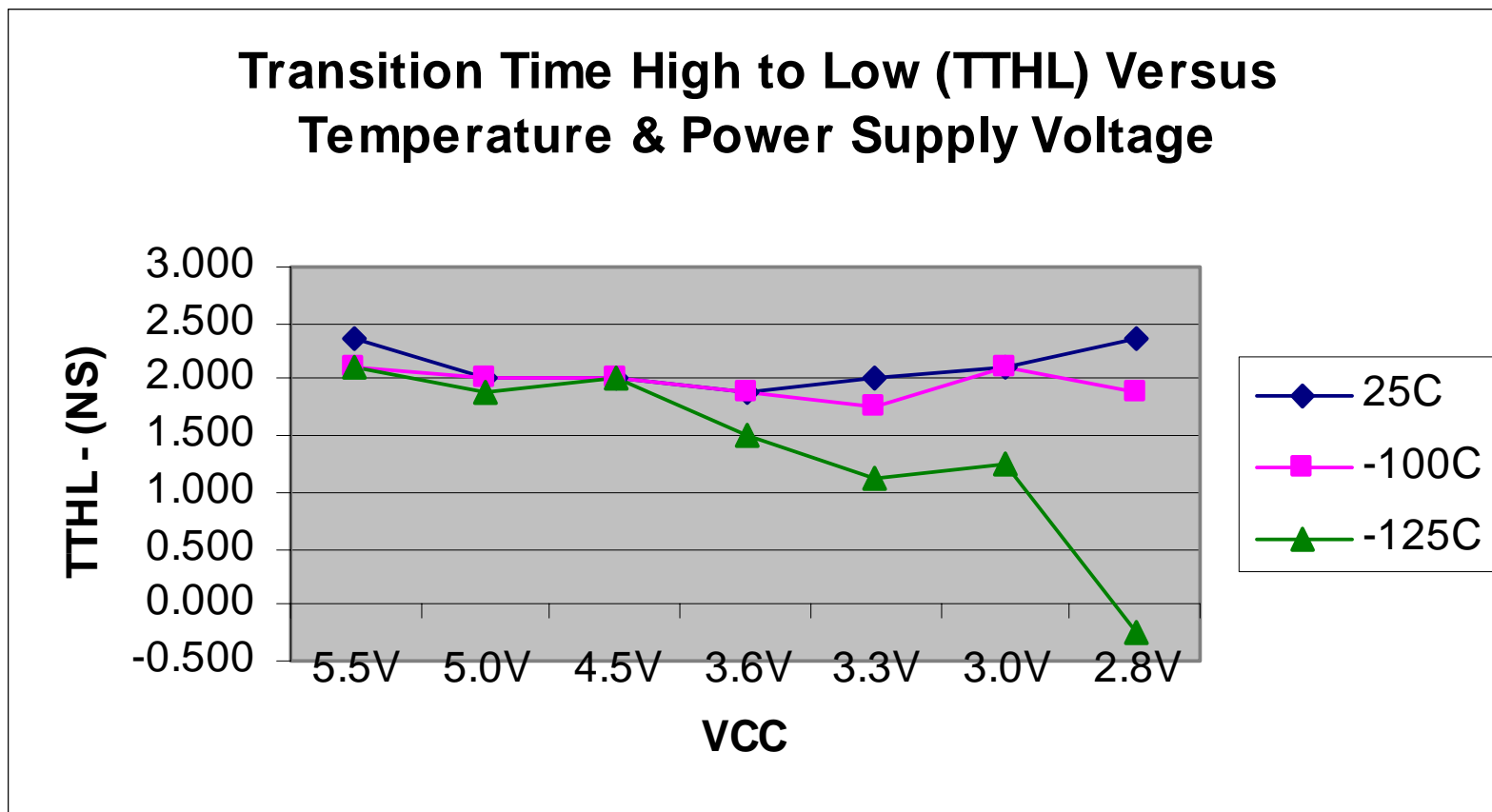


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- **The test results of the basic parameters of a radiation hardened quad receivers at extreme cold environment indicates that the device can be applied for the potential application in Mars exploration missions even at  $-125\text{ }^{\circ}\text{C}$  if the operating parameters such as power supply voltages chosen properly.**

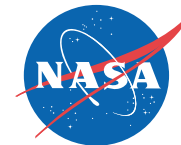
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## Performance of Rad-Hard Quad Receivers at Extreme Temperatures

- **We do not recommend using this part below 3V supply voltage in applications requiring operation down  $-125^{\circ}\text{C}$ .**
- **The output rise and fall times,  $t_{\text{TLH}}$  and  $t_{\text{THL}}$ , were well within the SMD max limits of 12ns at  $5\text{V} \pm 10\%$  and 15ns at  $3.3\text{V} \pm 10\%$ .**
- **The parts though exhibited anomalous behavior at the conditions of 2.8V supply voltage and low temperatures.**



## Acknowledgements



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### **Performance of Rad-Hard Quad Receivers at Extreme Temperatures**

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